

## Features

- Ultra Low Forward Voltage Drop
- Low Leakage Current
- Superior Reverse Avalanche Capability
- Excellent High Temperature Stability
- Patented Interlocking Clip Design for High Surge Current Capacity
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- 150°C Operating Junction Temperature
- **Lead Free Finish, RoHS Compliant (Note 1)**
- **“Green” Molding Compound (No Br, Sb)**

## Mechanical Data

- Case: PowerDI<sup>®</sup> 123
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity Indicator: Cathode Band
- Terminals: Finish - Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.018 grams (approximate)



Top View

## Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.  
 For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	200	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>RM</sub>		
Average Rectified Output Current (See Figure 1)	I <sub>O</sub>	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	40	A

## Thermal Characteristics

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance Junction to Ambient (Note 2)	R <sub>θJA</sub>	217	°C/W
Maximum Thermal Resistance Junction to Ambient (Note 3)	R <sub>θJA</sub>	138	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +175	°C

## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage	V <sub>F</sub>	-	0.75 0.60	0.82 0.68	V	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 25°C I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C
Reverse Current (Note 4)	I <sub>R</sub>	-	-	50	μA	V <sub>R</sub> = 200V, T <sub>J</sub> = 25°C
Reverse Recovery Time	t <sub>rr</sub>	-	-	25	ns	I <sub>F</sub> = 0.5A, I <sub>R</sub> = 1A, I <sub>RR</sub> = 0.25A

- Notes:
1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
  2. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.
  3. Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.
  4. Short duration pulse test used to minimize self-heating effect.

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SBR1U200P1

Document number: DS32093 Rev. 2 - 2

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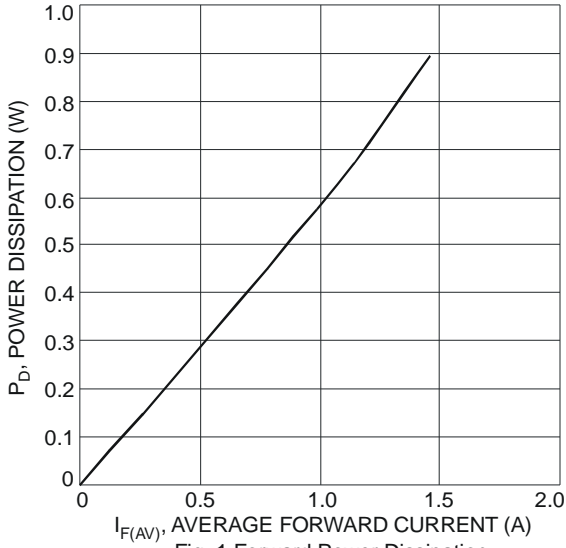


Fig. 1 Forward Power Dissipation

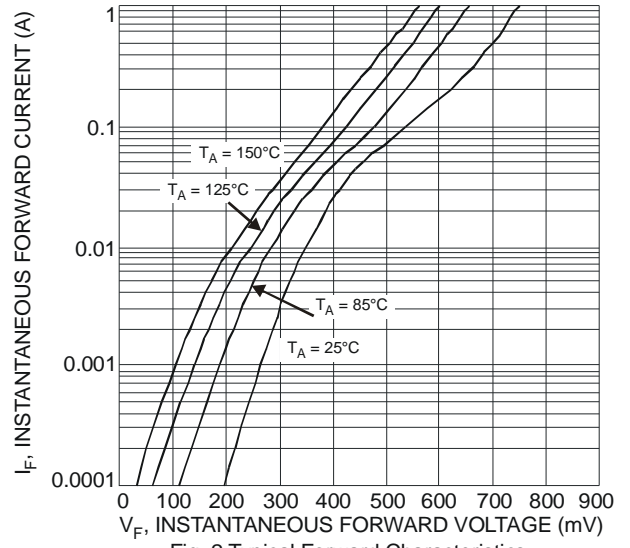


Fig. 2 Typical Forward Characteristics

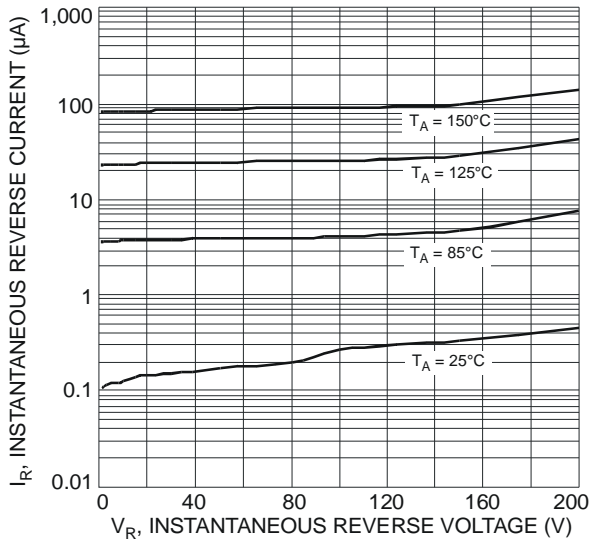


Fig. 3 Typical Reverse Characteristics

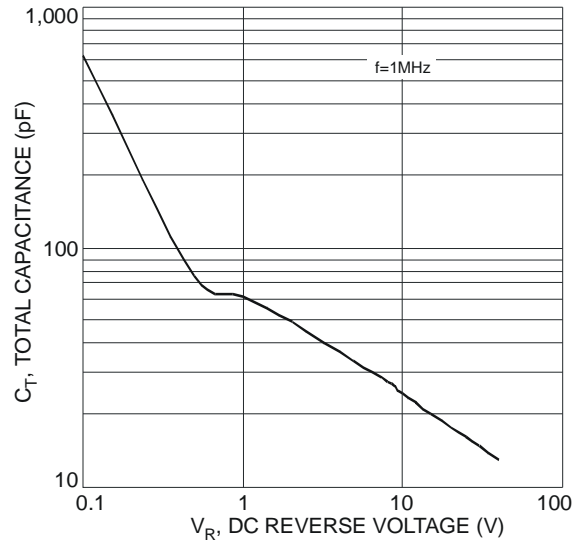


Fig. 4 Total Capacitance vs. Reverse Voltage

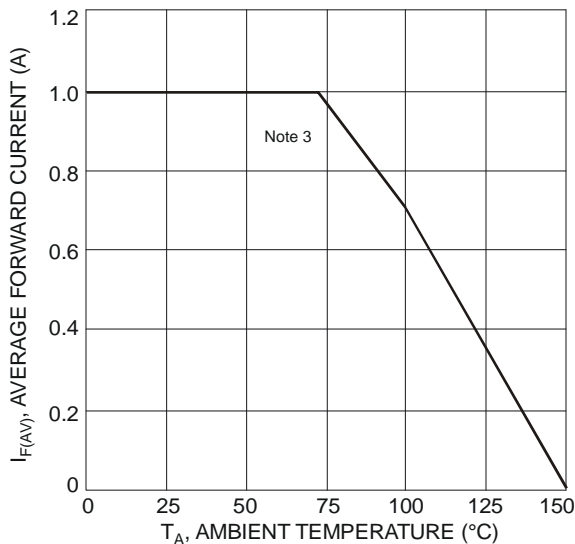


Fig. 5 Forward Current Derating Curve

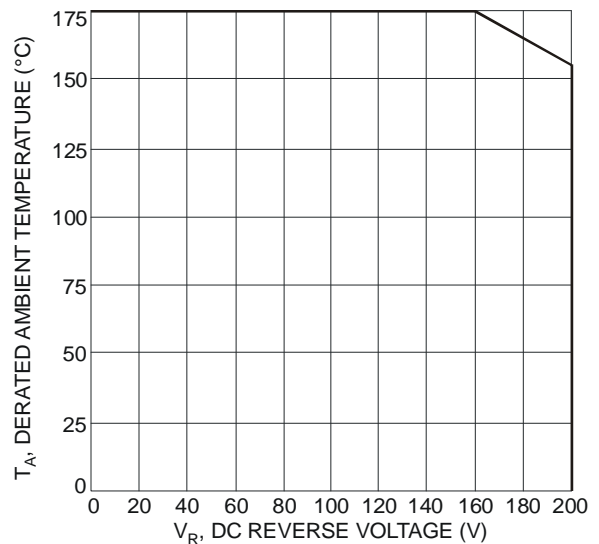


Fig. 6 Operating Temperature Derating

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**Ordering Information** (Note 5)

Part Number	Case	Packaging
SBR1U200P1-7	PowerDI <sup>®</sup> 123	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Marking Information**

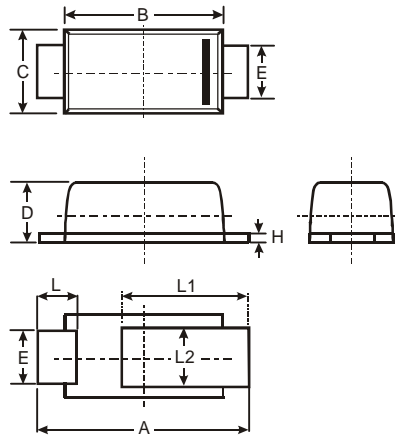

SDC = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: X = 2010)  
 M = Month (ex: 9 = September)

## Date Code Key

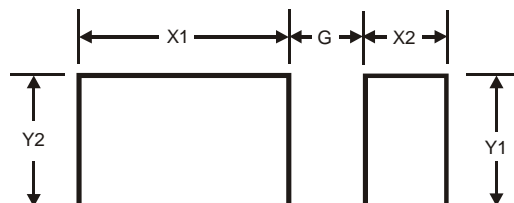
Year	2009	2010	2011	2012	2013	2014	2015
Code	W	X	Y	Z	A	B	C

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Package Outline Dimensions**


PowerDI <sup>®</sup> 123			
Dim	Min	Max	Typ
A	3.50	3.90	3.70
B	2.60	3.00	2.80
C	1.63	1.93	1.78
D	0.93	1.00	0.98
E	0.85	1.25	1.00
H	0.15	0.25	0.20
L	0.55	0.75	0.65
L1	1.80	2.20	2.00
L2	0.95	1.25	1.10
All Dimensions in mm			

**Suggested Pad Layout**


Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4

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